Electronic Patent Application Fee Transmittal								
Application Number:	10666399							
Filing Date:	18-Sep-2003							
Title of Invention:	Molded chip fabrication method and apparatus							
First Named Inventor/Applicant Name:	Michael S. Leung							
Filer:	Brian J. Philpott/Joan Harriman							
Attorney Docket Number:	P0298US-7							
Filed as Large Entity								
Utility under 35 USC 111(a) Filing Fees								
Description	Fee	Code	Quantity	Amount	Sub-Total in USD(\$)			
Basic Filing:	•							
Pages:								
Claims:								
Miscellaneous-Filing:								
Petition:								
Patent-Appeals-and-Interference:								
Post-Allowance-and-Post-Issuance:								
Extension-of-Time:								

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
	Tot	810		